

WAFER PREPARATION AND IODINE-ETHANOL PASSIVATION PROCEDURE FOR REPRODUCIBLE MINORITY-CARRIER LIFETIME MEASUREMENT

Bhushan Sopori, Przemyslaw (Peter) Rupnowski, Jesse Appel, Vishal Mehta, Chuan Li, and Steve Johnston

National Renewable Energy Laboratory • Golden, CO 80401

INTRODUCTION

CORE

• Measurement of the bulk minority-carrier lifetime (τ_b) by optical methods, such as photocurrent decay or quasi-steadystate photoconductance (QSSPC), is strongly influenced by surface recombination.

• Several techniques are known to lower the effective surface recombination velocity, including the following: use of oxidation, floating N/P junction, SiN:H layer, HF immersion, and use of iodine in ethanol or methanol (I-E solution).

• Using I-E appears to be very simple and does not require any high-temperature treatment such as oxidation, diffusion, or nitridation processes, which can change $T_{\rm b}$. • However, this is not a preferred procedure within the photovoltaic community because it is difficult to obtain same $T_{\rm b}$ values reproducibly, particularly when the wafer lifetime is long.

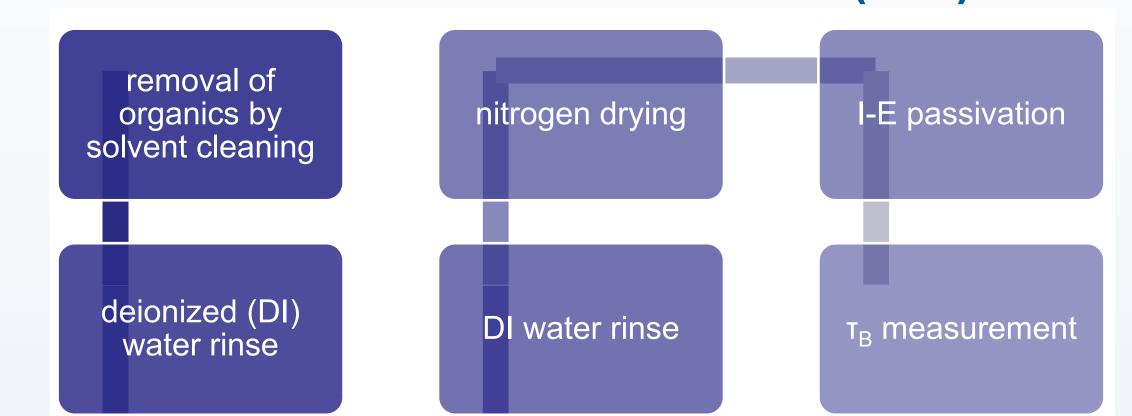
OBJECTIVES FOR STUDYING LIFETIME MEASUREMENTS AND I-E PASSIVATION

(i) Investigate various reasons why lifetime measurements may be irreproducible using I-E solution passivation.

(ii) Study the influence of the strength of iodine in the ethanol solution, wafer-cleaning procedures, influence of the wafer container during lifetime measurements, and the stability of I-E.

(iii) Compare lifetimes of wafers (having different $\tau_{\rm b}$) by various techniques such as QSSPC and transient photoconductive

INITIAL **CLEANING PROCEDURE (ICP)**



piranha

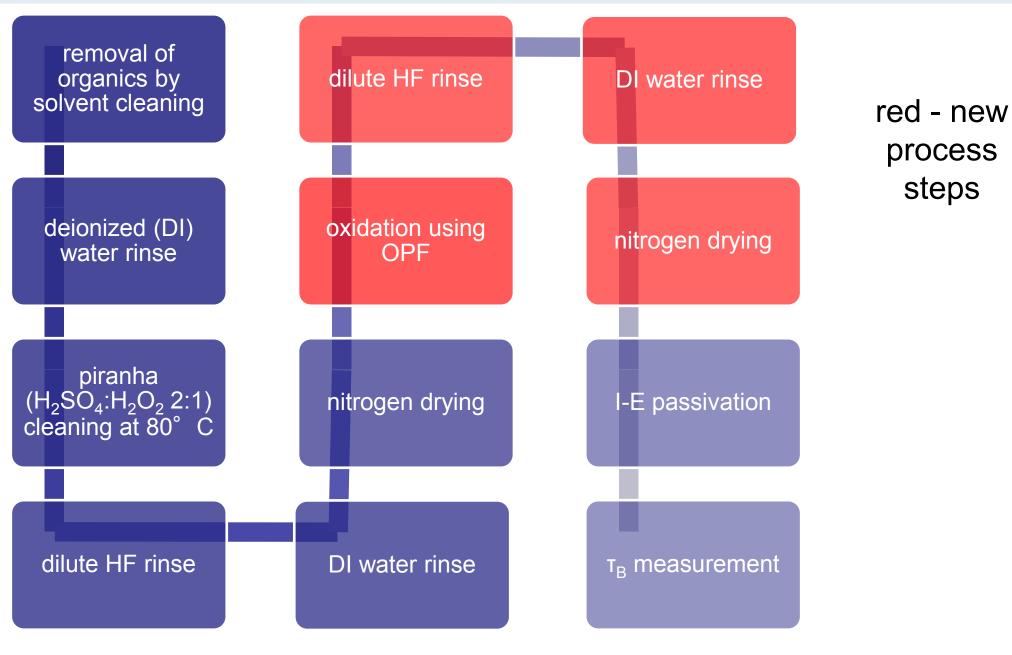
 $(H_2SO_4:H_2O_2 2:1)$

cleaning at 80° C

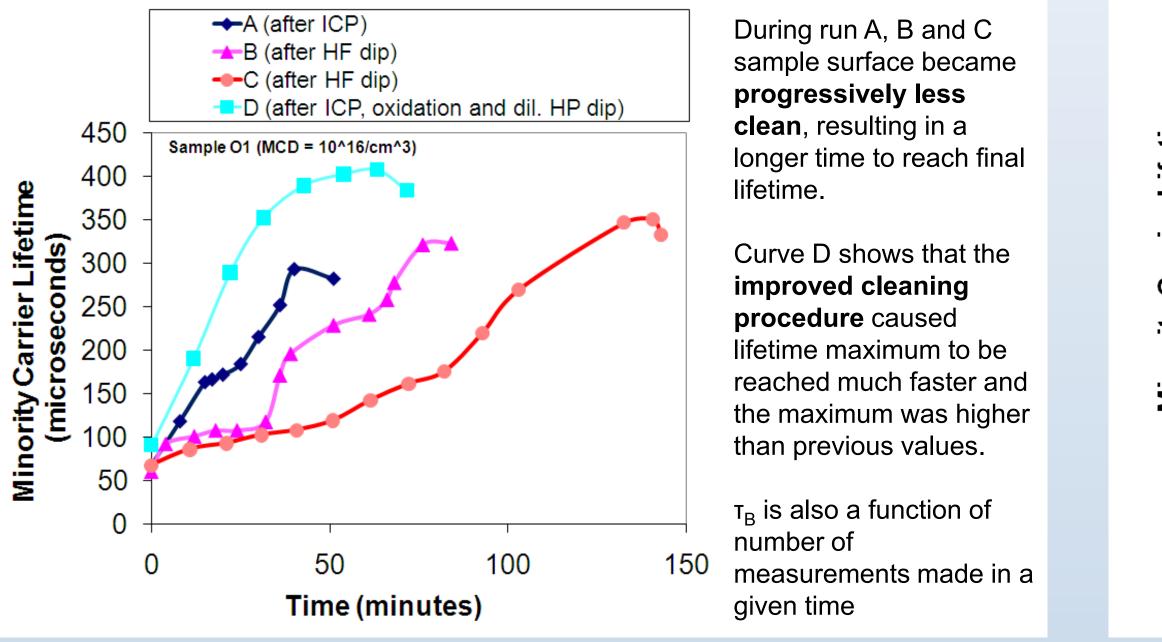
decay using short laser pulses of different light intensity;

(iv)Make minority-carrier diffusion length (L) measurements by a surface photovoltage technique, and to use T_{h} and L data to determine diffusivity (D) values for various impurity and defect concentrations, using the relationship $L^2 = D^* \tau_b$.

IMPROVED **CLEANING PROCEDURE**

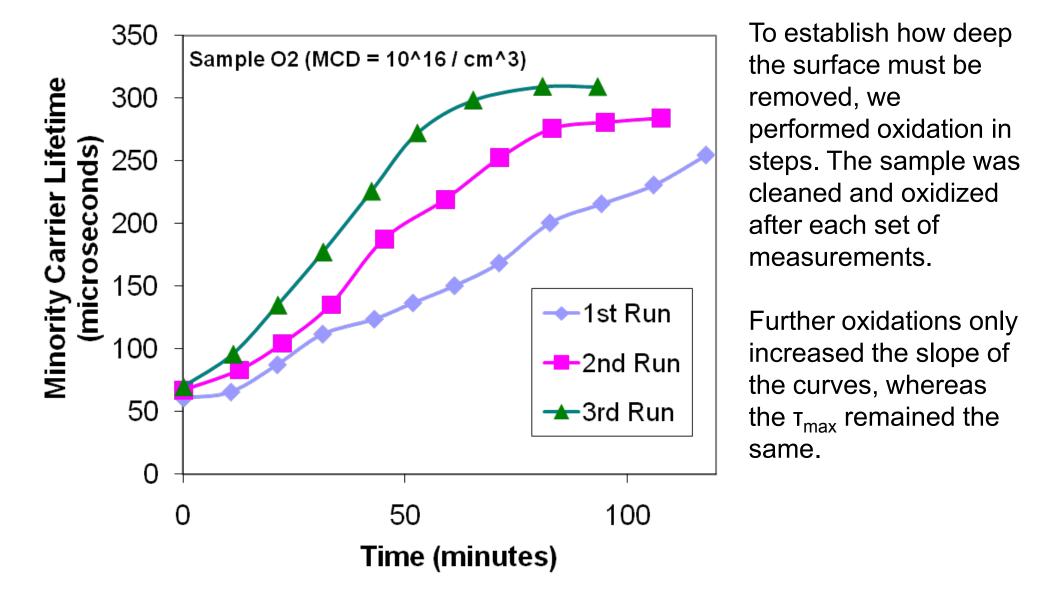


COMPARISION OF CLEANING PROCEDURES



RESULTS FOR SEQUENTIAL CLEANING

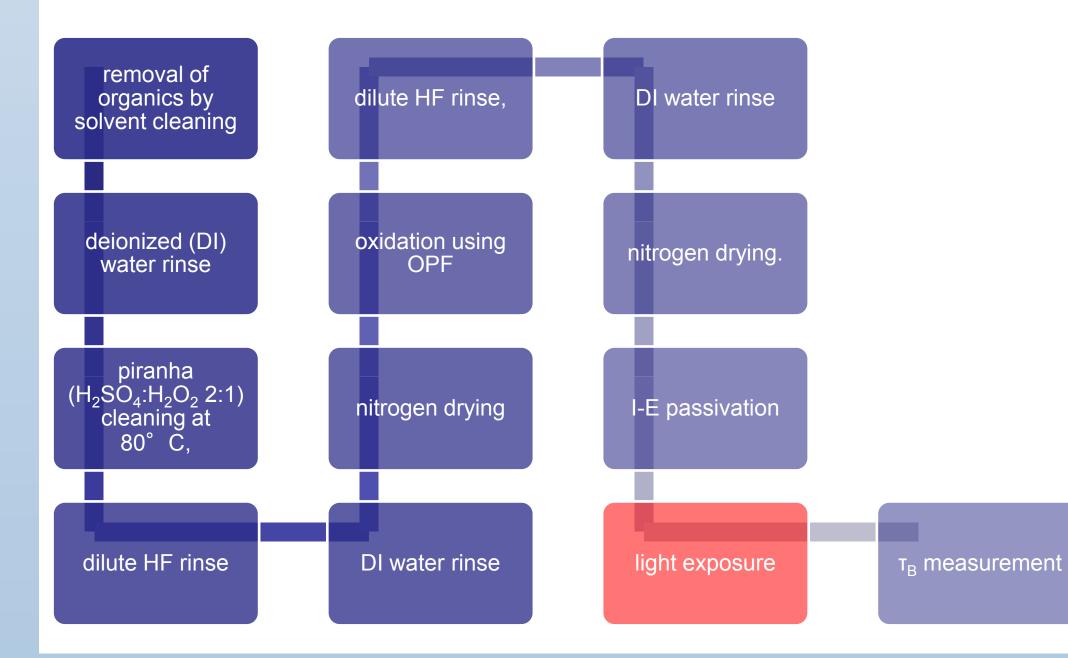
dilute HF rinse

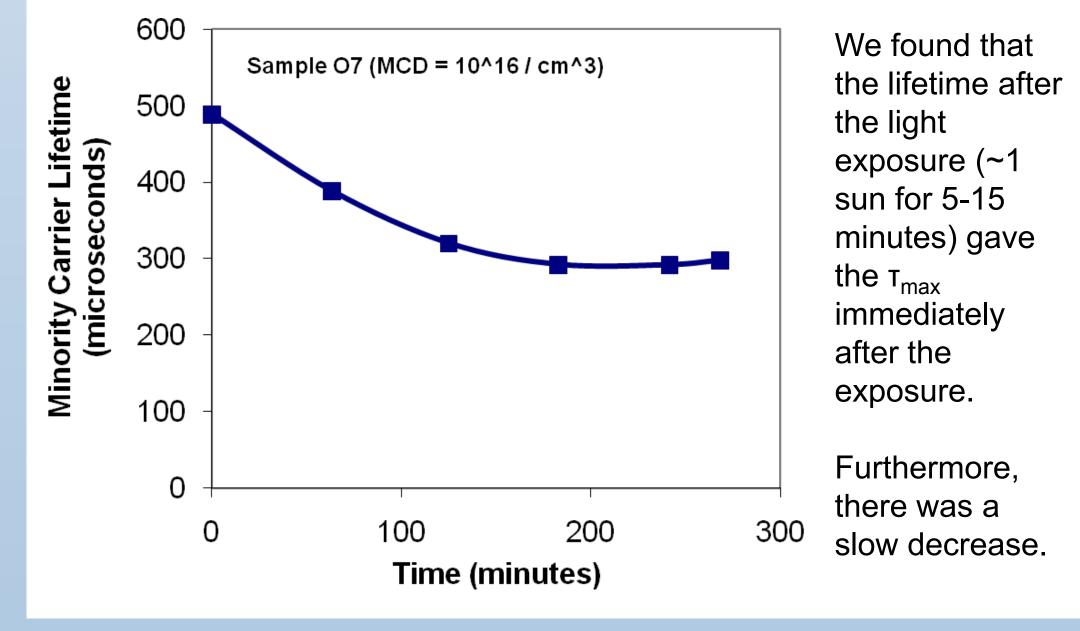


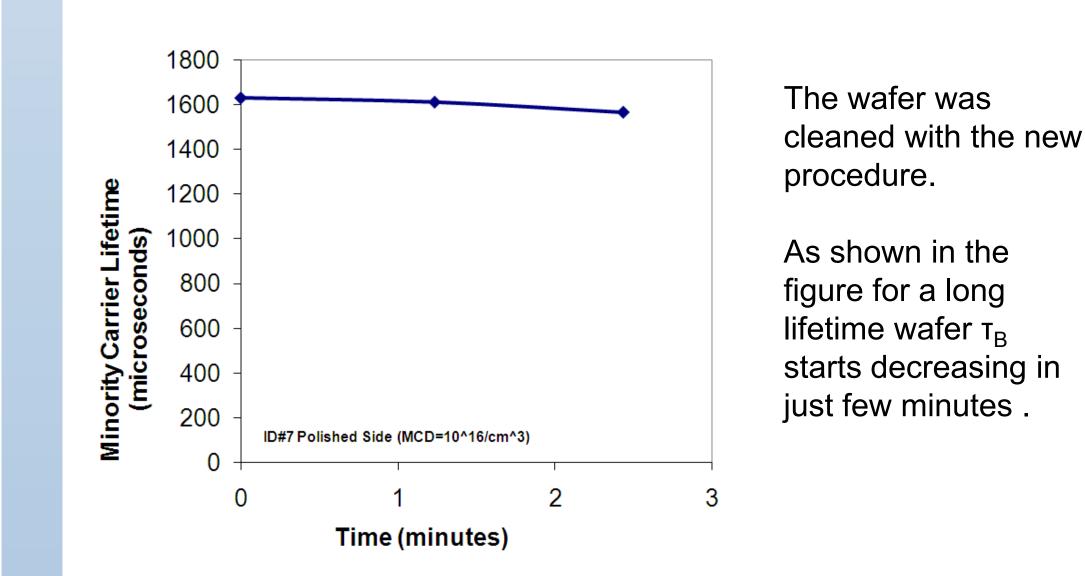
VARIATION OF T_R FOR A LONG LIFETIME WAFER

LIGHT EXPOSURE EFFECT

T_B DECAY AFTER LIGHT EXPOSURE





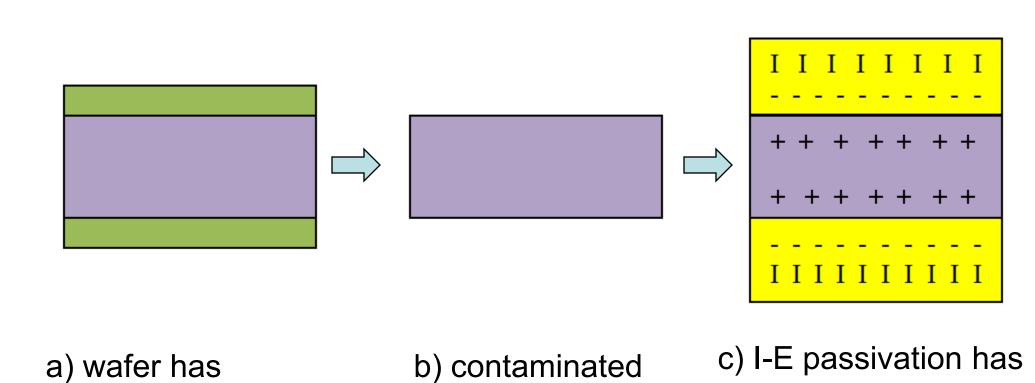


As shown in the figure for a long lifetime wafer T_B starts decreasing in just few minutes.

WHAT IS BEHIND THE LIGHT EFFECT?



SIMPLE MODEL FOR WAFER PREPARATION



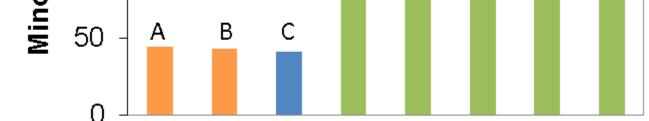
surface removed

CONCLUSIONS

• Wafer cleaning procedure should include removal of about 200–300 Å of Si from each surface.

• We have outlined a procedure that yields a very clean surface.

IE passivation may be sensitivity to light



Visible and IR-reach light source needs to be used to observe the light effect.

A and B - after 15 min. UV illumination C - after heating at 50°C for 15 min. D to H - after 5 min. 1 sun illumination

contamination/surface damage, which must be removed to get high degree of passivation

a time constant (charge accumulation filling surface traps), which is activated by light (depends on bulk properties)

• Unfortunately, our data on a variety of wafers are not consistent. For example, wafers from the same lot do not have the same dependence of lifetime on light exposure.

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